

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims 27-42, AMEND claims 22-26, and ADD new claims 43 in accordance with the following:

Claims 1-21 (canceled)

22. (Currently Amended) An arrangement, comprising:
~~at least one a~~ a substrate;
~~at least one an~~ an electrical component arranged on a surface section of ~~each the~~ the substrate, ~~each the~~ the electrical component having an electrical contact surface; and
~~at least one an~~ an electrical contact lug, ~~each~~ including
 ~~at least one an~~ an electrically-conductive film having an electrical connection surface in electrical contact with the contact surface of ~~at least one of said at least one electrical~~ component, and
 an area protruding beyond the contact surface of ~~the at least one of said at least one electrical~~ component.

23. (Currently Amended) An arrangement according to claim 22, wherein the ~~at least one electrically-conductive film~~ is a laminated interconnect having ~~at least two electrical conductor layers~~ and ~~at least one an~~ an electrical insulation layer arranged between the ~~at least two electrical conductor layers~~.

24. (Currently Amended) An arrangement in accordance with claim 23, wherein the ~~at least two electrical conductor layers~~ and the insulation layer of the laminated interconnect are arranged to produce opposing magnetic fields in the ~~at least two electrical conductor layers~~ upon electrical activation.

25. (Currently Amended) An arrangement according to claim 24, wherein the ~~at least two electrical conductor layers~~ of the laminated interconnect are substantially in a coplanar

arrangement.

26. (Currently Amended) An arrangement in accordance with claim 25, wherein the ~~at least one~~ electrical component is a power semiconductor chip.

27-42. (Cancelled).

43. (New) An electronic device, comprising:

a substrate;

a power semiconductor chip arranged on a surface section of the substrate, the power semiconductor chip having an electrical contact surface; and

an electrical contact lug having

a laminated interconnect as an electrically-conductive film in electrical contact with the contact surface of the power semiconductor chip, the laminated interconnect having at least two electrical conductor layers, which are substantially in a coplanar arrangement, and at least one electrical insulation layer arranged between the at least two electrical conductor layers, the at least two electrical conductor layers and the insulation layer being arranged to produce opposing magnetic fields in the at least two electrical conductor layers upon electrical activation, and

an area extending beyond the contact surface of said electrical component.